
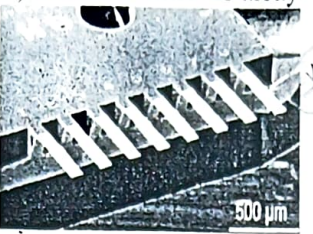


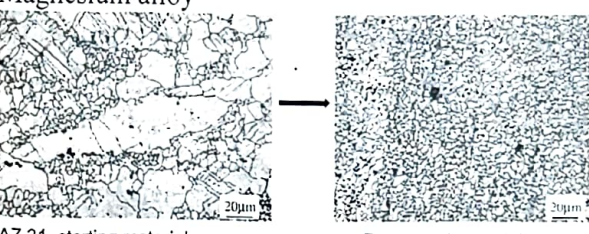

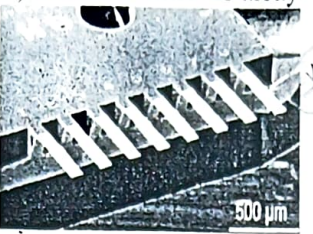


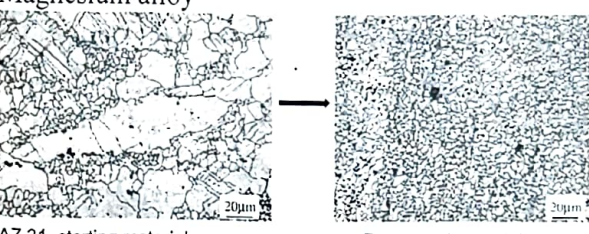

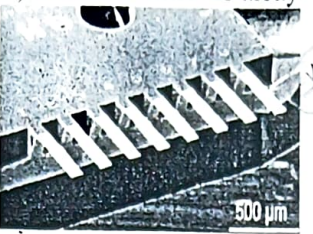


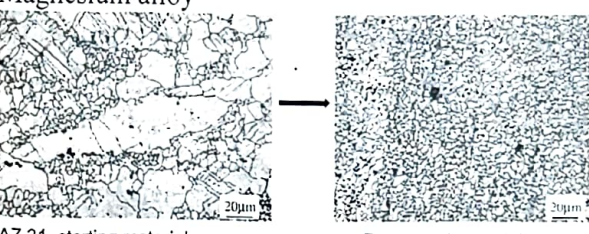


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|---------------------------------------|--|
| Micro and Nano Manufacturing (MCL331) | B.Tech., MAJOR |
| Max.Marks : 40 | Date: 5 th April 2022 LH 308 Time: 8.15 am – 10.15 am |

Answer all questions, Neat sketches and drawings carry weightage
 Make suitable assumptions wherever required, and state your assumption.

| | | | | | | | | |
|--|--|--|--|---|--|--|--|---------|
| 1 | <p>Explain the manufacturing process of the following, with necessary process parameters for the fabrication and uses of the same (with neat sketches)</p> <table border="1" data-bbox="175 409 1204 997"> <tr> <td data-bbox="175 409 587 703"> <p>A) Nickel Micro mould</p>  </td> <td data-bbox="587 409 939 703"> <p>B) Silicon cantilever array</p>  </td> <td data-bbox="939 409 1204 703"> <p>C) WC armor plate</p>  </td> </tr> <tr> <td data-bbox="175 703 587 997"> <p>D) Free standing Diamond Tube</p>  </td> <td colspan="2" data-bbox="587 703 1204 997"> <p>Magnesium alloy</p>  <p>AZ 31 starting material Processed material</p> </td> </tr> </table> | <p>A) Nickel Micro mould</p>  | <p>B) Silicon cantilever array</p>  | <p>C) WC armor plate</p>  | <p>D) Free standing Diamond Tube</p>  | <p>Magnesium alloy</p>  <p>AZ 31 starting material Processed material</p> | | 5x5 =25 |
| <p>A) Nickel Micro mould</p>  | <p>B) Silicon cantilever array</p>  | <p>C) WC armor plate</p>  | | | | | | |
| <p>D) Free standing Diamond Tube</p>  | <p>Magnesium alloy</p>  <p>AZ 31 starting material Processed material</p> | | | | | | | |
| 2 | Comment and state the reason for the difference in the nose radius of a PCD tool and a single crystal diamond tool. | 3 | | | | | | |
| 3 | Comment on the growth of diamond film on magnesium. | 3 | | | | | | |
| 4 | <p>Specify the process involved in the following cases.</p> <ol style="list-style-type: none"> FeB at HSS surface Removal of deposited aluminum layer from the silicon substrate Maskless etching | 3 | | | | | | |
| 5 | Write the difference between dose and fluence in a beam processing | 3 | | | | | | |
| 6 | Write on intelligent cutting tool | 3 | | | | | | |

LIGA
MUSH

PM
+SPS